WHAT IS CLAIMED IS:

1. A powder supply apparatus that supplies a powder containing a metal used for a plating to a plating solution, the powder supply apparatus comprising:

a plating solution tank configured to house the plating solution; and

a hopper that houses the powder, wherein

the hopper includes a feed port and an exhaust port, the feed port being configured to feed the powder into the hopper, the exhaust port discharging a gas in the hopper, and

the powder supply apparatus further comprises:

a first scatter preventing component configured to prevent the powder from scattering from a clearance between the feed port and a feed nozzle, the feed nozzle being configured to feed the powder to the feed port; and

a second scatter preventing component configured to prevent the powder from scattering from the exhaust port.

2. The powder supply apparatus according to claim 1, wherein

the first scatter preventing component includes a filter cloth, the first scatter preventing component being mounted to the feed port or the feed nozzle.

3. The powder supply apparatus according to claim 1 or 2, wherein

the second scatter preventing component includes a filter cloth, the second scatter preventing component being mounted to the exhaust port.

4. The powder supply apparatus according to any one of claims 1 to 3, wherein

the feed nozzle is a nozzle of a powder container that houses a powder.

5. The powder supply apparatus according to any one of claims 1 to 3, further comprising

an intermediate nozzle that receives a powder fed from a nozzle of a powder container housing the powder, the intermediate nozzle feeding the powder to the feed port of the hopper, wherein

the feed nozzle is the intermediate nozzle.

6. The powder supply apparatus according to claim 5, wherein

the first scatter preventing component is mounted to the intermediate nozzle, and

the first scatter preventing component is configured such that when the powder is fed to the hopper, the first scatter preventing component contacts the feed port of the hopper.

7. A plating system comprising:

the powder supply apparatus according to any one of claims 1 to 6;

a plating bath configured to plate a substrate; and

a plating solution supply pipe that extends from the plating solution tank of the powder supply apparatus to the plating bath.